FASTMath Team Members: Max Bloomfield, Brian Granzow, Glen Hansen, Dan Ibanez, Jake Ostien, Seegyoung Seol, Mark Shephard, Cameron Smith

Integration of unstructured mesh technologies with advanced solution methods to impact complex multiphysics applications

Component-Based Unstructured Mesh Simulat

FASTMath components support construction of simulation workflo

- Parallel mesh infrastructure and services
- Dynamic load balancing
- Parallel fields and error estimators

FASTMATH

• Parallel mesh optimization/adaptation

Integration with analysis codes to construct adaptive simulation I

- File-based integration requires no analysis code modification • Often first approach implemented
- In-memory methods developed that minimize code modification • Improves efficiency – avoids I/O bottleneck

Integration with component-based analysis code provides increas flexibility and performance opportunities

- Albany FE code based on Agile Component approach
- Take advantage of Trilinos and Dakota components
- In-memory integration for adaptivity natural
- Opportunities for optimization and uncertainty quantification

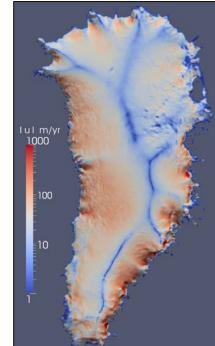
Albany – Agile Components

A parallel, implicit, unstructured mesh finite element code

- Being applied to problems from ice sheet modeling to large deformation based structural failures
- Build on over 100 component pieces
- Components include

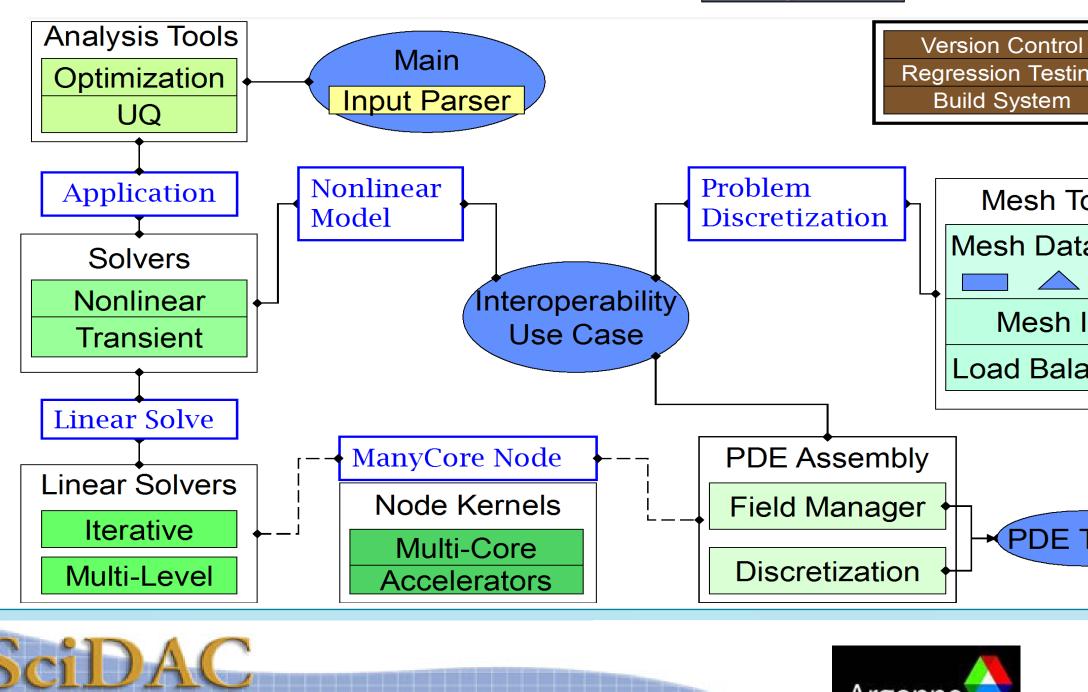
• Libraries – solvers, UQ, Optimization

- Interfaces parallel meshes
- Software quality control tools
- Demonstration applications



Greenland Sheet **Surface Veloc** constant friction mo

Argonne



Scientific Discovery through Advanced Computing

Component-Based Unstructured Mesh Simulation Workflows

ion		Component-Based Adaptive Simulation
ows		Goal is to execute massively parallel, automated, adaptive sim
		 Employ a component-based approach using FASTMath
		unstructured mesh components – PUMI, APF, Zoltan, ParMA MeshAdapt
		 Support direct geometry interfaces design data
oops		 Integrated with automatic meshing technologies
0003		 Support both file-based and/or in-me analysis codes
ns		 Key current development efforts Parallel fields
		Generalized error estimation library
sed		 Multiple load balancing methods to improve parallel efficiency
		Parallel adaptive loops developed to date:
		 Modeling of nuclear accidents and various flow problems wi PHASTA (meshes up-to 92B elements on ³/₄ cores)
		 Accelerator modeling problems with SLAC's ACE3P code
		 Fusion MHD with PPPL's M3D-C1 code
		 Solid mechanics applications with Albany (see boxes to righ
		 Aerodynamics problems with NASA's Fun3D code
		 Waterway flow problems with ERDC's Protous code
		Leading-edge 5 synthetic jets
		14 up - baseline 14 down - basel
ce		
ities odel)		14 up - forced 14 down - force
		Physics and Model Parameters Input Domain Definition with Attri
		Solution transfer constraints model const
		Local Soln. MeshSim, Gmsh, etc.
Ig		transfer operation geometric interrogation
		PDE's and meshes and mesh size mesh discretization fields field
		methods mesh size mesh size
ools abase		field Domain Topology - PUMI
		Library Mesh Linkage - PUMI geometry update
/0		mesh with fields Simulation Fields - APF
incing		ALBANY Partition Control - PUMI Para
		calculated fields Dynamic Load Balancing – mesh with fields Zoltan, ParMA mesh with fields
Terms		Parallel Adaptive Simulations with Albany
		More Information: http://www.fastmat
~	Δ.	Sandia
BERKELEY] " LAB	Lawrence Livermore National Laboratory

Modeling Large Deformation Structural Failures nulations Adaptive simulations of finite deformation plasticity with Albany • Projects include modeling large deformations and weld failures Efforts to develop adaptive loops that support Solution accuracy via error estimation • • High quality element shapes at all load steps • Accurate solution transfer of state variables • Predictive load balancing (ParMA, Zoltan) at each adaptive stage Mechanical Modeling of Integrated Circuits Microelectronics processing is very exacting and mechanical responses impact reliability and manufacturability th Multi-layer nature of chips interacts with temperature swings, creep, and intrinsic stress of films • Parallel adaptive simulations of wafer deformation using industry layout formats as inputs to model construction • Intrinsic stress in film deposited onto surface and into features causes macroscopic deflection of wafer – Interferes with further processing • Creep occurs in solder joints during use, (below) Displacement vs delamination during cool-down time curves for combined thermo-elastic, plastic, • Developed combined constitutive model and creep model. of thermoelastic, plastic, and creep contributions in ALBANY utes (right) automatically generated model and nanifold mesh from layout file including thin film. truction 0.1 Time (s) 0.05 (above) Wafer deflection (scaled) Future Plans rasolid, • Tighter integration to geometric model including smooth geometry mSim, update for adapting for large deformations, automatic geometry construction, distributed geometry • Curved mesh adaptation to support higher order methods • Generalization of the error estimation procedures and move to goal oriented adaptation /iew Adjoint calculation component for use in error estimation, optimization and uncertainty quantification th-scidac.org or contact Lori Diachin, LLNL, <u>diachin2@llnl.gov</u>, 925-422-7130 UBC STONY BROKK G Berkeley SMU. UNIVERSITY OF

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